



**NOTES:**

**MATERIAL:**

- 1. HOUSING MATERIAL :GLASS FILLED POLYESTER(U194V-0).
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE T=0.35mm (C5191).
- 3. PLATING :GOLD PLATING OVER NICKEL.

**ELECTRICAL:**

- 1. VOLTAGE RATING :125 VAC RMS.
- 2. CURRENT RATING :1.5 AMP.
- 3. CONTACT RESISTANCE :50 MILLIOHMS MAX.

4. INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.  
RESISTANCE

**MECHANICAL:**

- 1. DURABILITY :750 CYCLES MIN.
- 2. PCB RETENTION PRE-SOLDER

**ENVIRONMENTAL:**

- 1. STORAGE :-40°C TO +85°C.
- 2. OPERATION : 0°C TO 70°C.

MATES WITH MODULAR PLUG CONFORMING TO  
FCC PART 68,SUBPART F.

PART NUMBER: SMT-N1188-H33X

- GOLD PLATING U"
  - 1-F" 2-2u" 3-3u" 4-6u"
  - 5-15u" 6-30u"
- PLASTIC MATERIAL&COLOR:Black/Yellow/Gray
  - 1-PBT+20%GF Black
  - 2-PA46 Black
  - 3-LCP Black

REV	MODIFICATION	DATE	DRAW	APPROVE
A		2012/10/29	JDL	Oscdr

DIMENSION IN mm [Inch]		Shinhwa Tech Co., LTD			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.20	X.± 1°	FILE NO.	DWG NO. YLSMT-N1188-H3		
.XX±0.15	.X.± 0.5°	TITLE	SMT 1X1 gpgc PCB JACK V/O SHIELDED H=12.7MM ,TDP ENTRY,FLAT PIN		
.XXX±0.075		APPROVE	CHECK	DRAW	Oscdr
				PROL	SCALE 1:1
				SHEET	SIZE A3
				1	REV A